

P-Channel Enhancement MOSFET

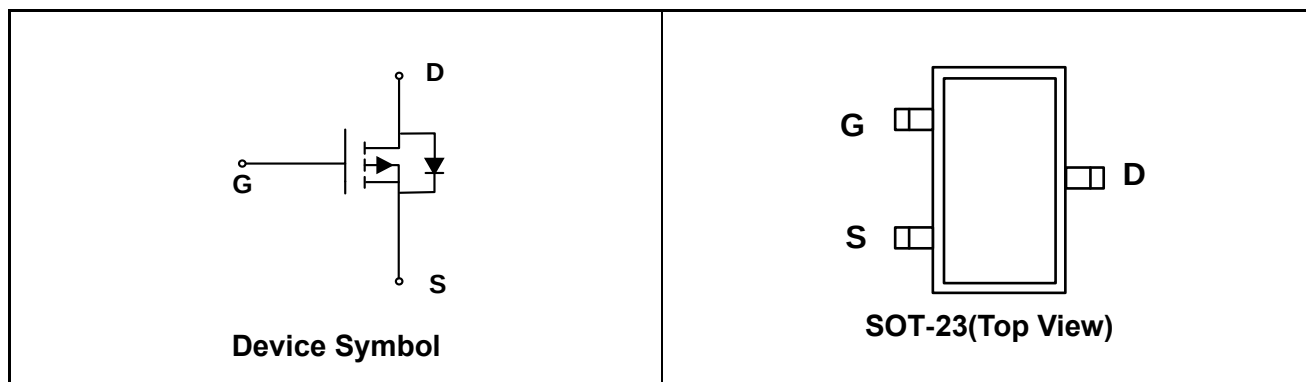
Features

- Small Signal MOSFETs
- $V_{DS} = -40V$, $I_D = -5A$
 $R_{DS(on)} < 85m\Omega$ @ $V_{GS} = -10V$
 $R_{DS(on)} < 125m\Omega$ @ $V_{GS} = -4.5V$
- Trench LV MOSFET Technology

Mechanical Characteristics

- Marking : Making Code
- RoHS Compliant & Halogen-Free
- SOT-23 Package

Schematic & PIN Configuration



EM04P50M

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	-40	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_A = 25^\circ\text{C}$	I_D	-5	A
Pulsed Drain Current ⁽¹⁾		I_{DM}	-20	A
Total Power Dissipation	$T_A = 25^\circ\text{C}$	P_D	1.2	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient ⁽²⁾	$R_{\theta JA}$	104	$^\circ\text{C/W}$

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Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-40	-	-	V
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -40V, V _{GS} = 0V	-	-	-1	μA
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D = -250μA	-1.2	-1.5	-2.5	V
Drain-Source on-state Resistance ⁽³⁾	R _{DS(on)}	V _{GS} = -10V, I _D = -5A	-	68	85	mΩ
		V _{GS} = -4.5V, I _D = -4A	-	84	125	
Dynamic Characteristics ⁽⁴⁾						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = -20V, f = 1MHz	-	553	-	pF
Output Capacitance	C _{oss}		-	50	-	
Reverse Transfer Capacitance	C _{rss}		-	42	-	
Switching Characteristics ⁽⁴⁾						
Total Gate Charge	Q _g	V _{GS} = -10V ,V _{DS} = -20V, I _D = -5A	-	11.8	-	nC
Gate-Source Charge	Q _{gs}		-	2.2	-	
Gate-Drain Charge	Q _{gd}		-	3	-	
Turn-on Delay Time	t _{d(on)}	V _{DD} = -20V, V _{GS} = -10V, R _G = 3Ω, I _D = -5A	-	7	-	ns
Rise Time	t _r		-	6.5	-	
Turn-off Delay Time	t _{d(off)}		-	24	-	
Fall Time	t _f		-	7.8	-	
Source-Drain Body Diode Characteristics						
Diode Forward Voltage ⁽³⁾	V _{SD}	I _S = -5A, V _{GS} = 0V	-	-	-1.2	V
Continuous Source Current	I _S		-	-	-5	A

Note1: Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)} = 150^\circ\text{C}$

Note2: The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.

Note3: Pulse Test: Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

Note4: This value is guaranteed by design hence it is not included in the production test

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Typical Characteristics

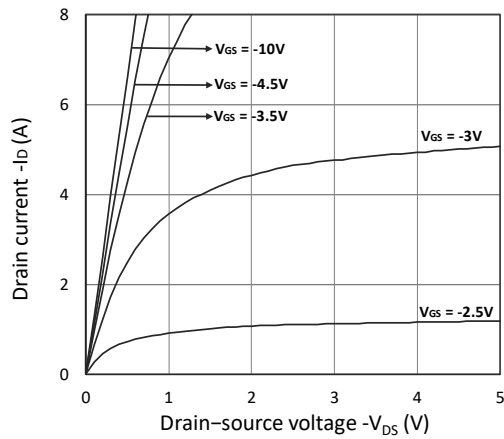


Figure 1. Output Characteristics

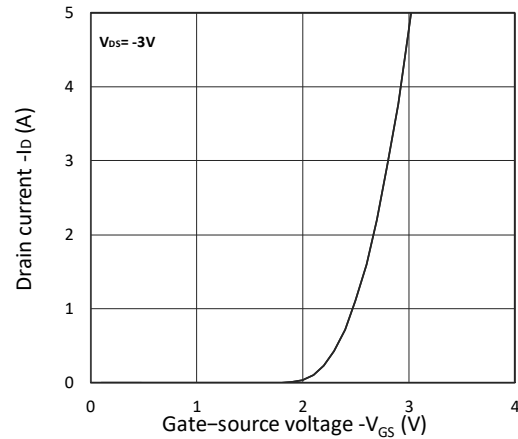


Figure 2. Transfer Characteristics

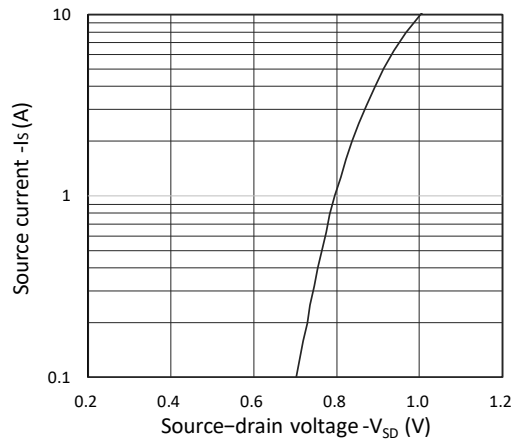


Figure 3. Forward Characteristics of Reverse

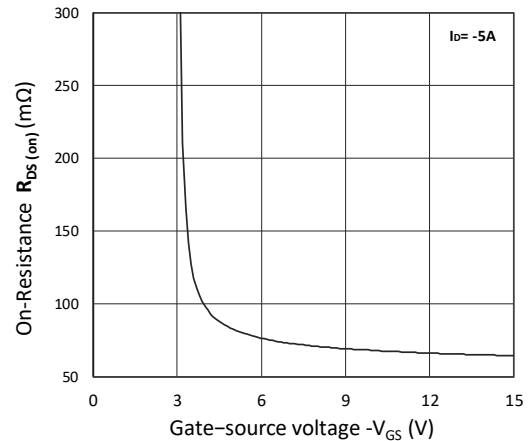


Figure 4. $R_{DS(on)}$ vs. V_{GS}

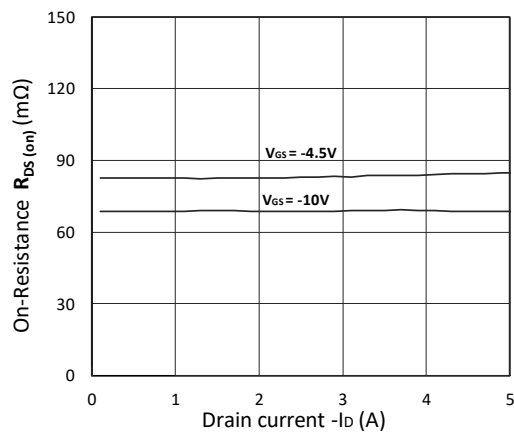


Figure 5. $R_{DS(on)}$ vs. I_D

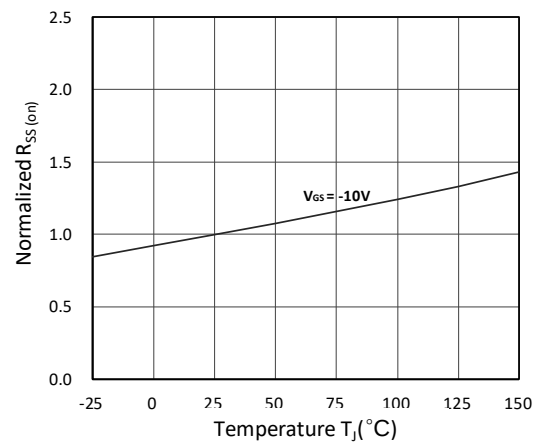


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

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Typical Characteristics(Continued)

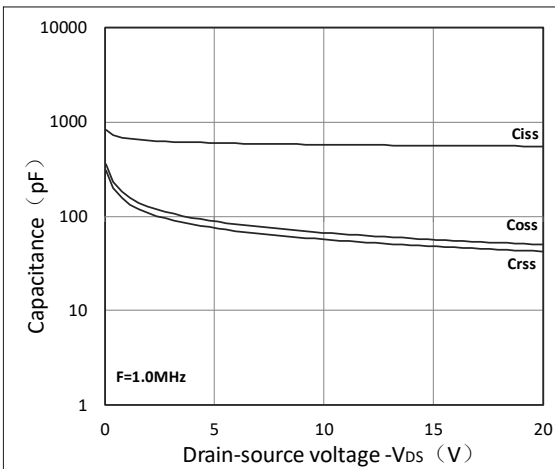


Figure 7. Capacitance Characteristics

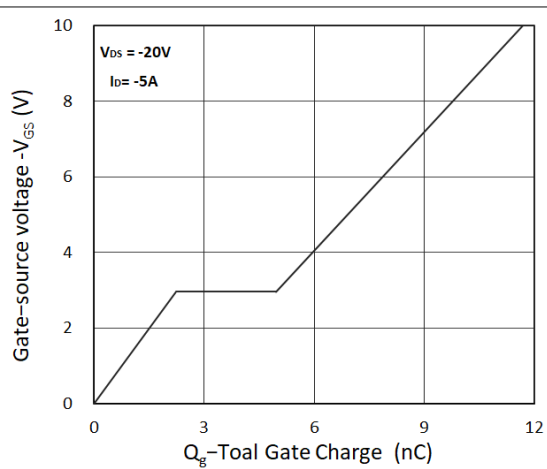


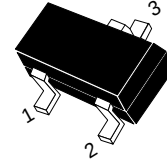
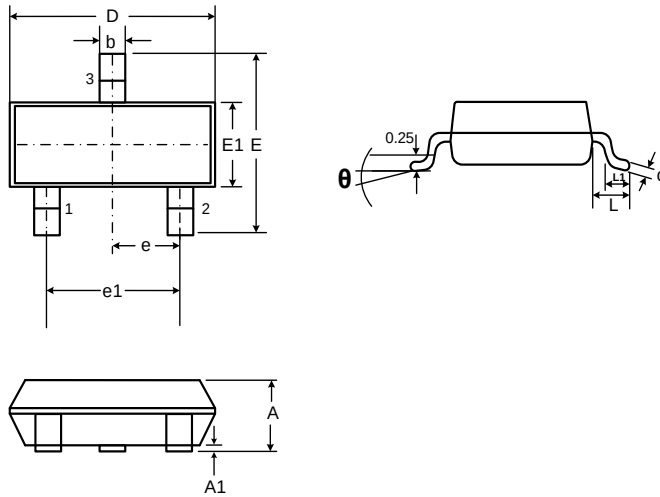
Figure 8. Gate Charge Characteristics

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Package Dimension

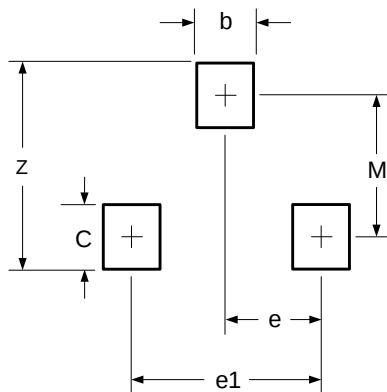
SOT-23

PACKAGE OUTLINE



SOT-23

SYMBOL	MILLIMETER	
	MIN	MAX
A	0.90	1.15
A1	0.00	0.10
b	0.30	0.50
c	0.08	0.15
D	2.80	3.00
E	2.25	2.55
E1	1.20	1.40
e	0.95 BSC	
e1	1.80	2.00
L	0.55REF	
L1	0.30	0.50
θ	0°	8°



DIMENSIONS	
DIM	MILLIMETERS
M	2.02
C	0.80
Z	2.82
e	0.95 BSC
e1	1.90 BSC
b	0.80

Ordering Information

Part	Package	Marking	Packing Information
EM04P50M	SOT-23	0450	3k/Reel

EM04P50M

Revision History and Checking Table

Version	Date	Revision Item	Modifier	Function & Spec Checking	Package & Tape Checking
1.0	2023-12-13	Released Version	Qin Pei Long	Qi Shu Kun	Liu Jia Ying